

3 MeV Proton Irradiation Study of Ultra-thin GaAs Solar Cells

Larkin Sayre¹, Armin Barthel¹, Andrew Johnson², Louise Hirst^{1,3}

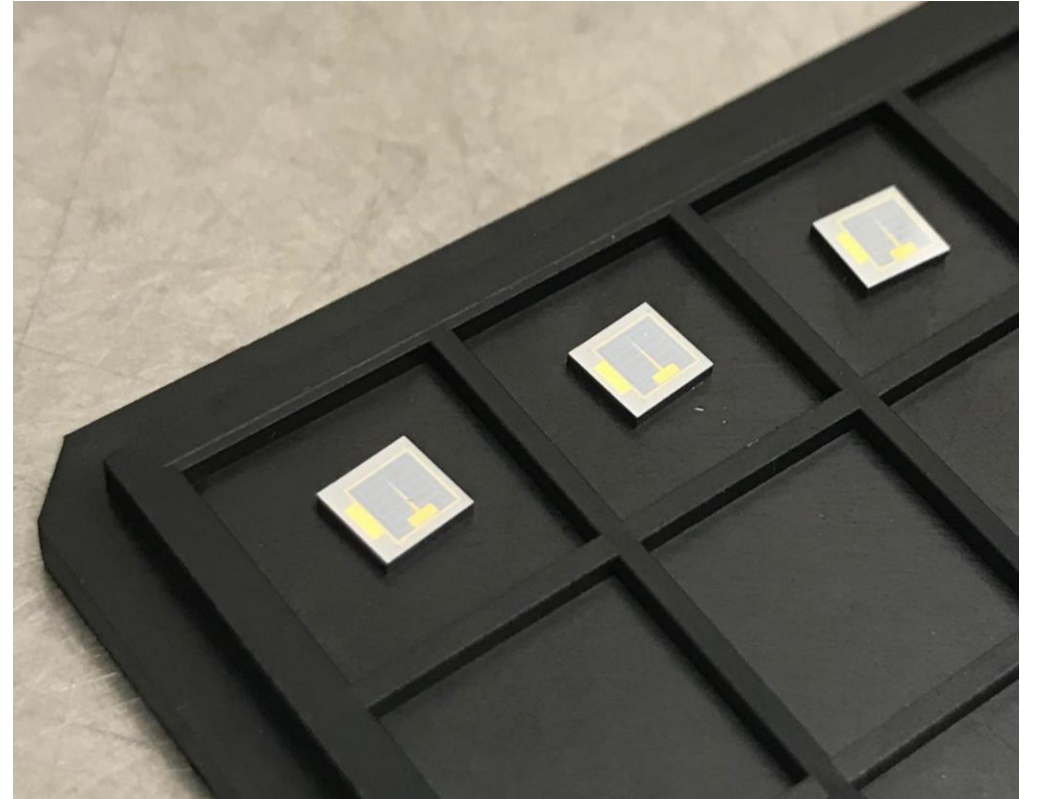
¹Department of Materials Science & Metallurgy, University of Cambridge, UK

²IQE plc., Cardiff, UK

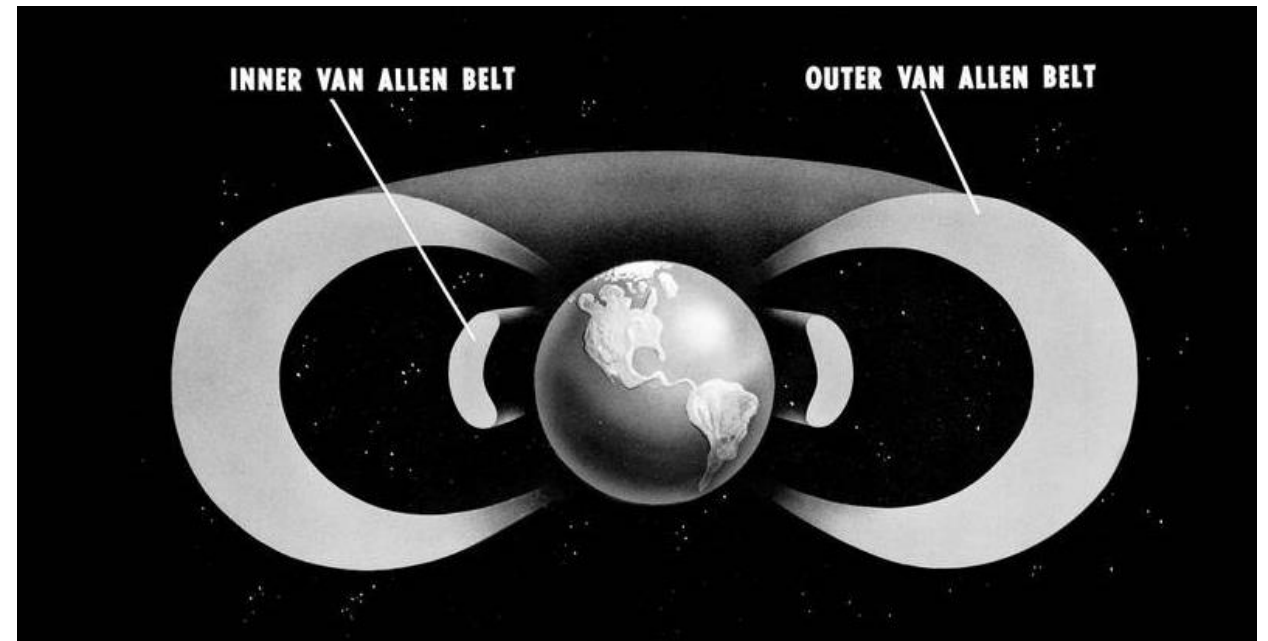
³Department of Physics, University of Cambridge, UK

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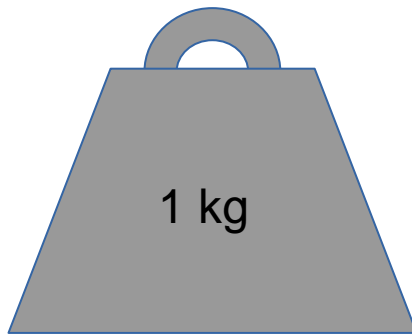
- Background
- Device design
- Fabrication process
- Results
 - Pre-exposure electrical characterisation
 - 3 MeV proton irradiation
- Conclusions
- Future work



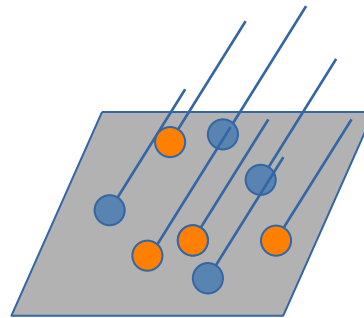
- Outside of the Earth's protective atmosphere there are regions with high levels of damaging radiation
- Satellite mission lifetimes are limited by radiation damage of solar arrays
- Radiation tolerant solar cells could open up currently inaccessible orbits and space missions



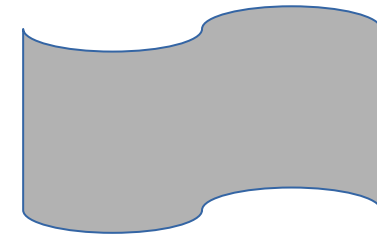
Key metrics/attributes of space photovoltaics:



High specific power

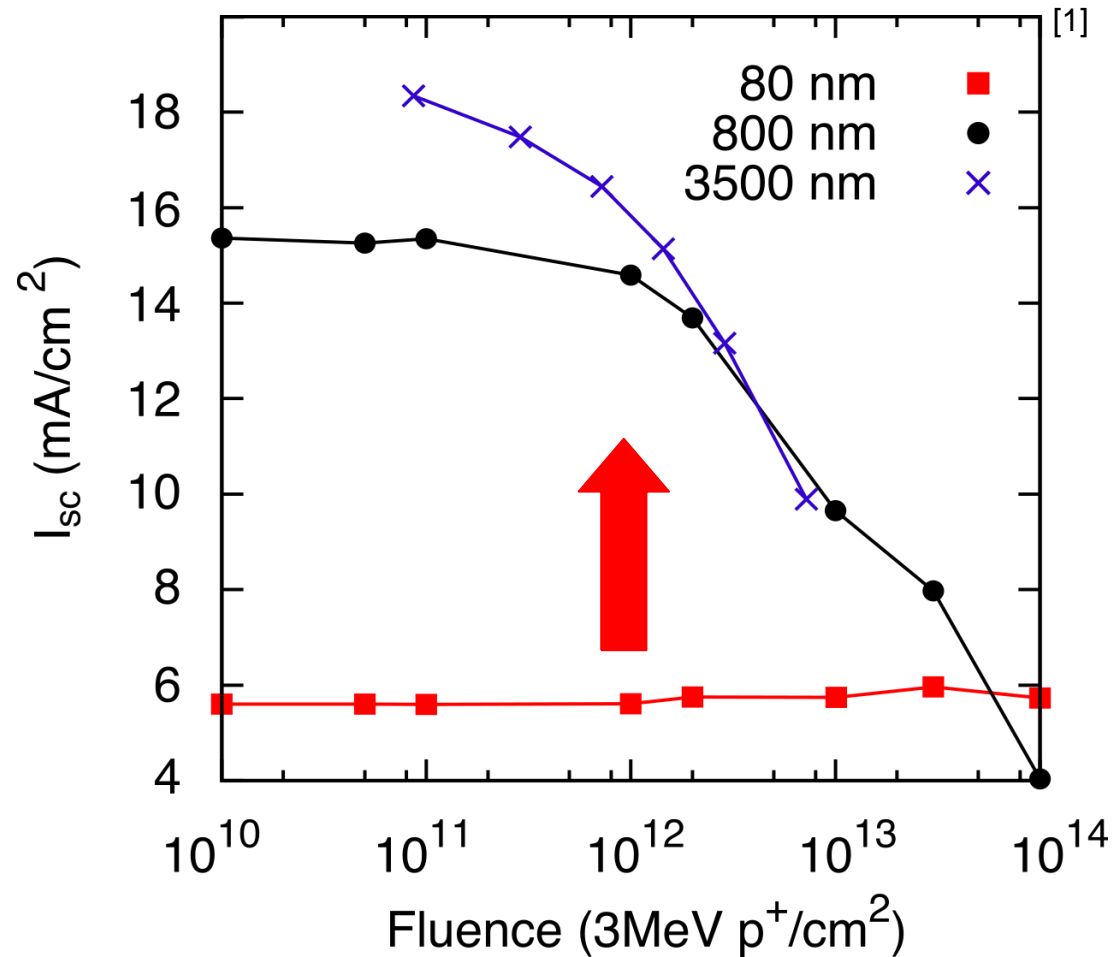


Radiation tolerance



Flexible form factors

- Ultra-thin (<100 nm absorber layer) solar cells have shown intrinsic radiation tolerance¹
- High transmission losses need to be mitigated
- Previous studies have achieved 19.9% AM1.5 efficiency for a 205 nm GaAs absorber layer with an integrated light-trapping layer²



Goal: Boost absorption while maintaining radiation tolerance through the use of a nanophotonic light-trapping layer

Table 1: Layer structure of ultra-thin cells as grown by molecular beam epitaxy

Layer	Material	Dopant	Doping density (cm ⁻³)	Nominal thickness (nm)	Measured thickness (nm)
n-type contact	GaAs	Si	5x10 ¹⁸	300	318
Hole barrier	In _{0.47} AlP	Si	5x10 ¹⁸	20	17
n-type absorber	GaAs	Si	1x10 ¹⁸	40	87
p-type absorber	GaAs	Be	1x10 ¹⁸	40	
Electron barrier	In _{0.49} GaP	Be	5x10 ¹⁸	20	19
p-type contact	GaAs	Be	1x10 ¹⁹	25	25
Etch stop layer	InAlP	Be		150	145
Buffer	GaAs	Be		300	
Substrate	p-GaAs				

Fabrication process

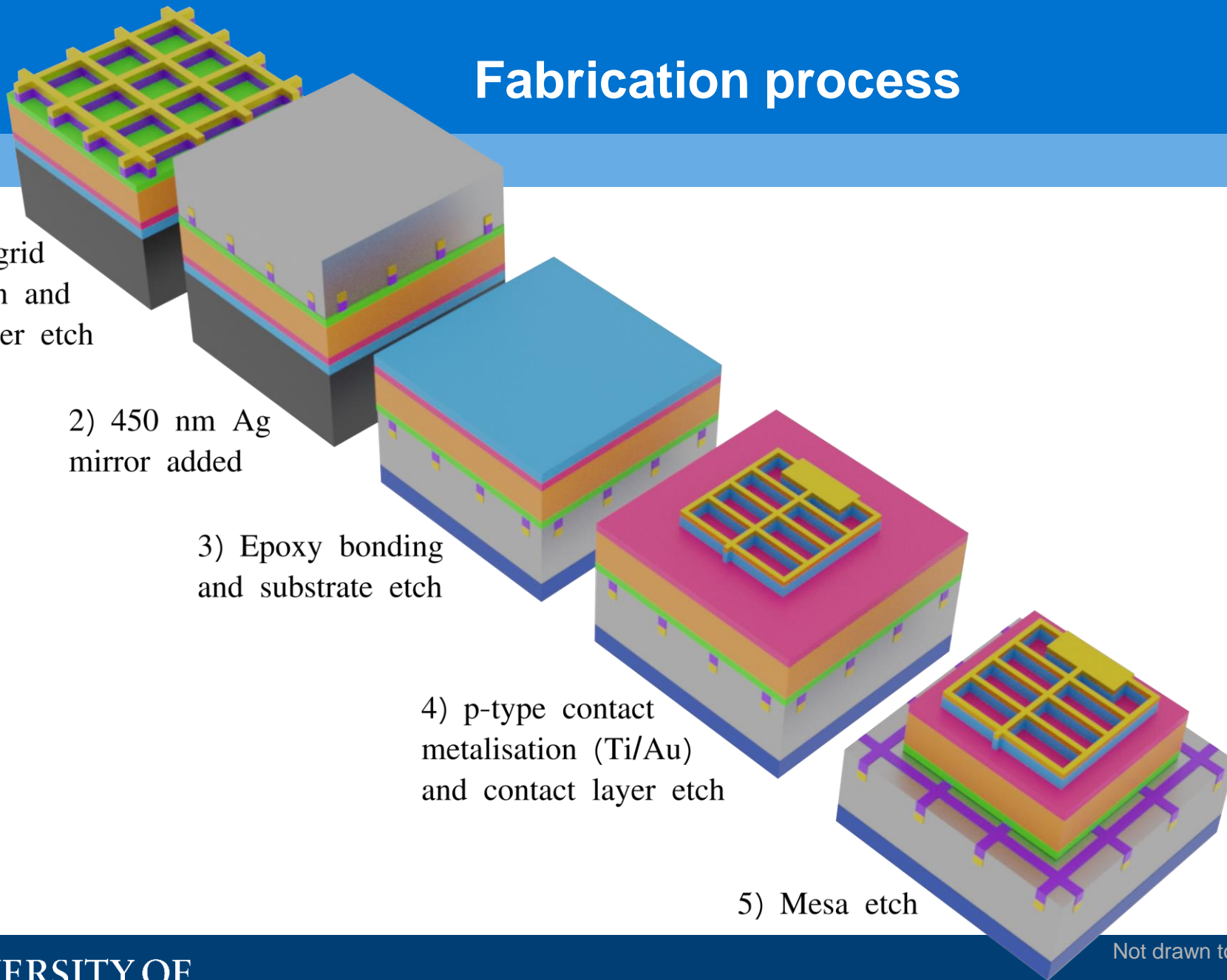
1) n-type grid
metalisation and
contact layer etch

2) 450 nm Ag
mirror added

3) Epoxy bonding
and substrate etch

4) p-type contact
metalisation (Ti/Au)
and contact layer etch

5) Mesa etch



Not drawn to scale

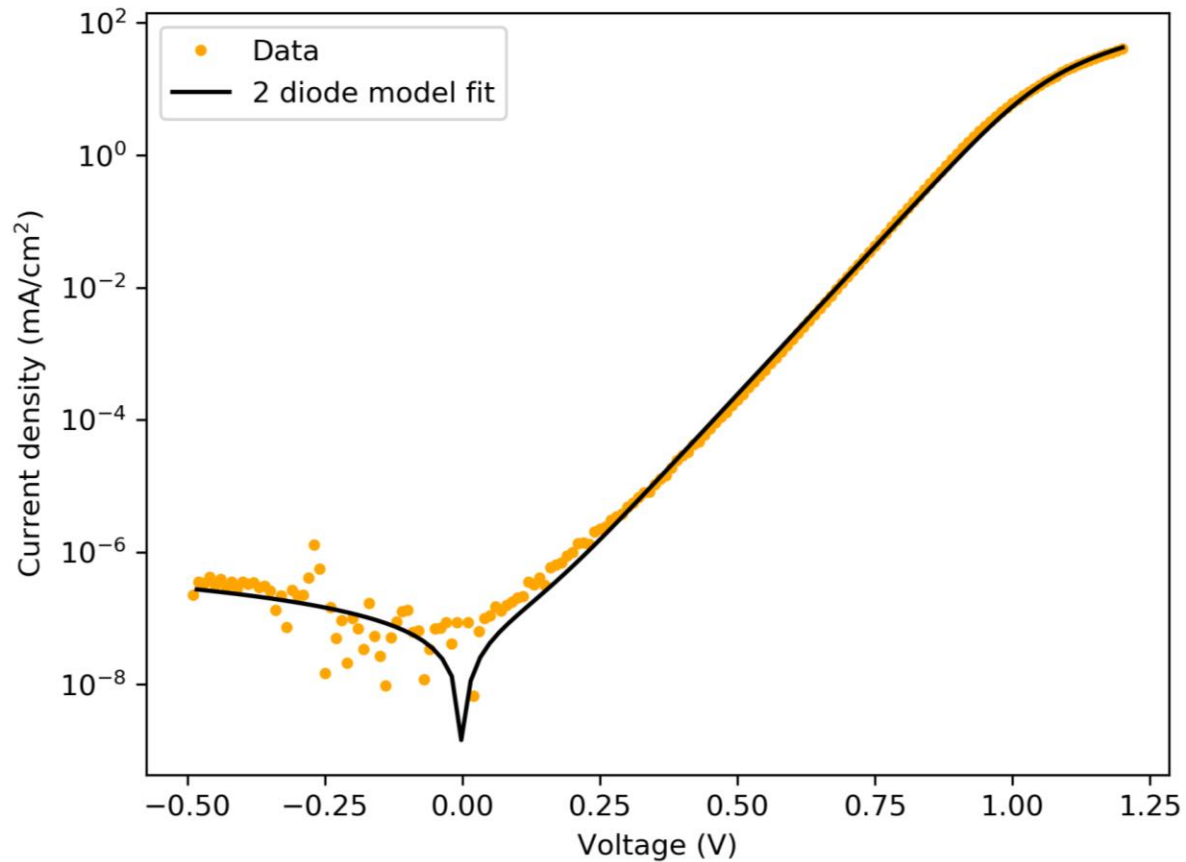
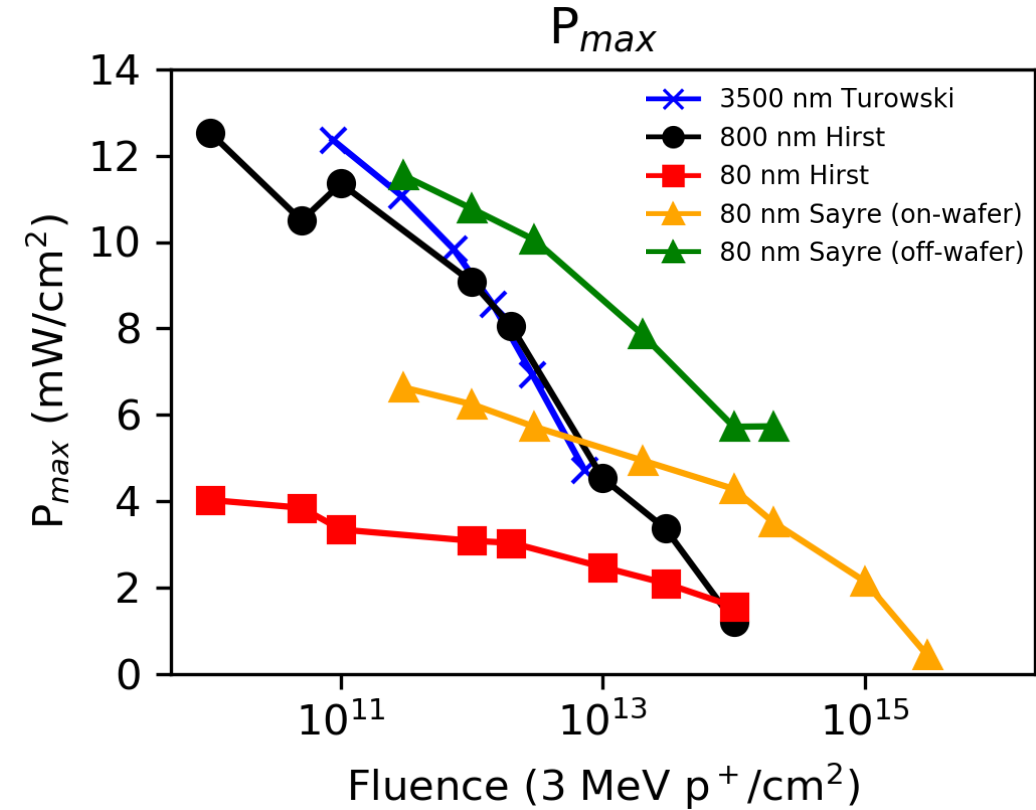
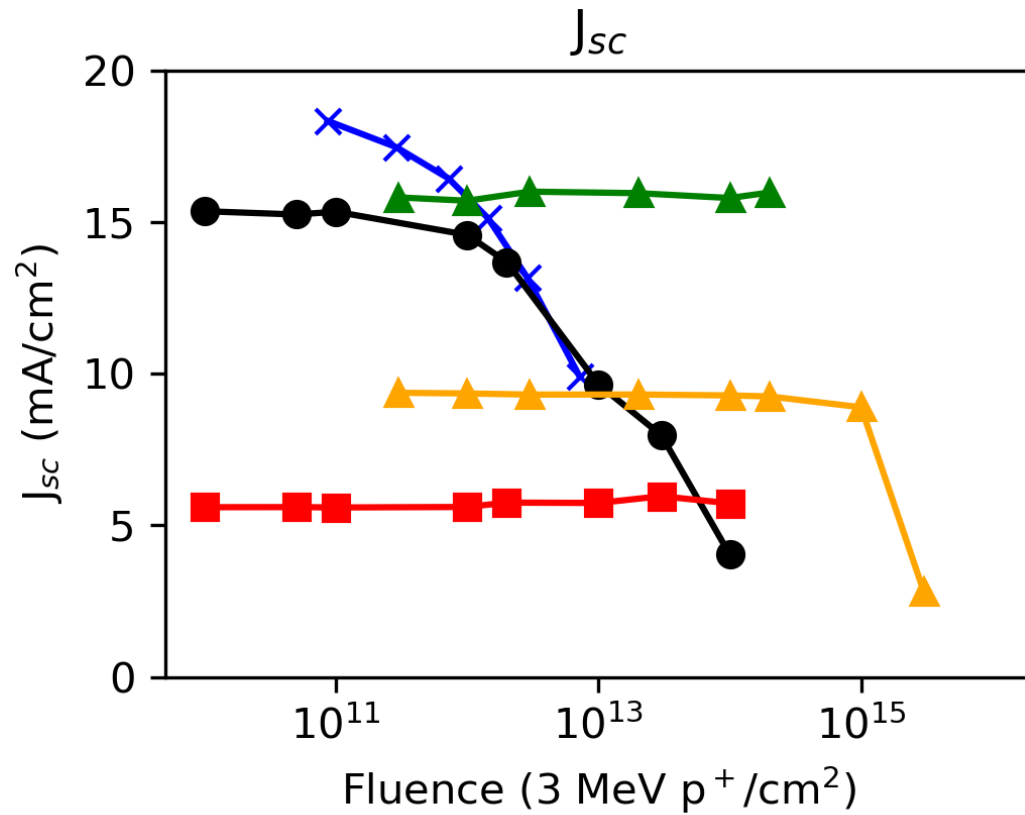


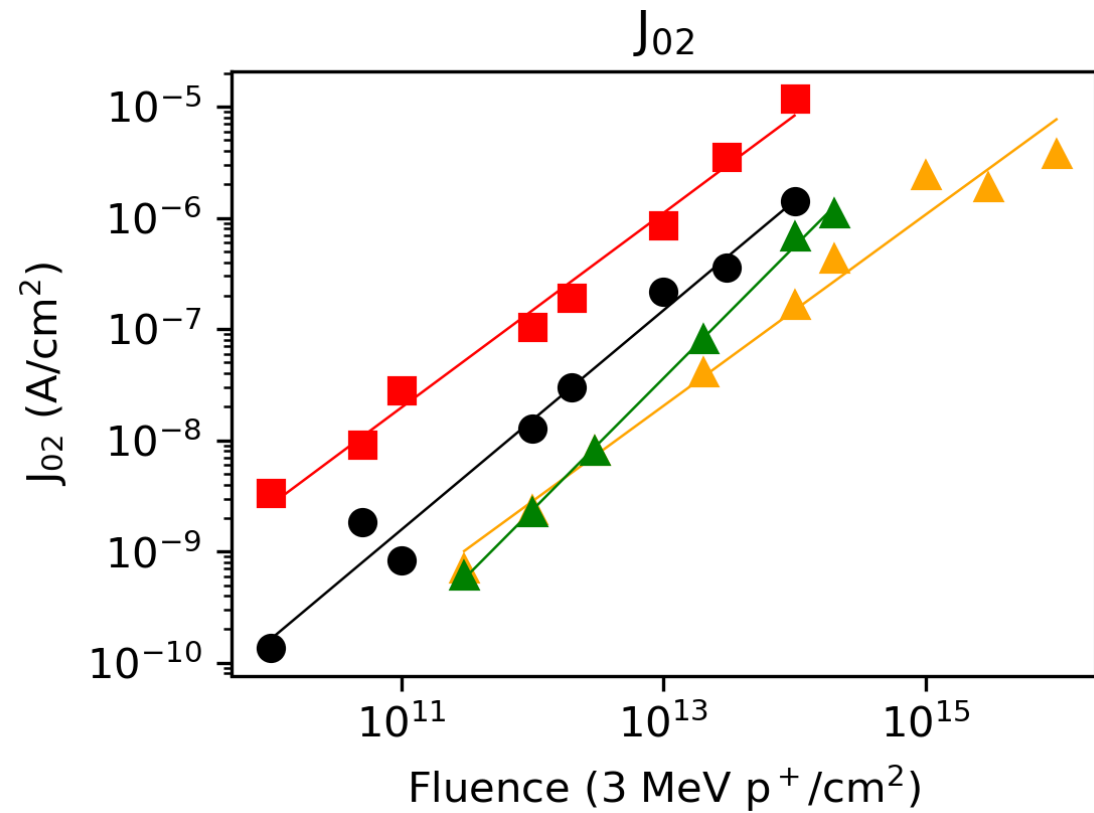
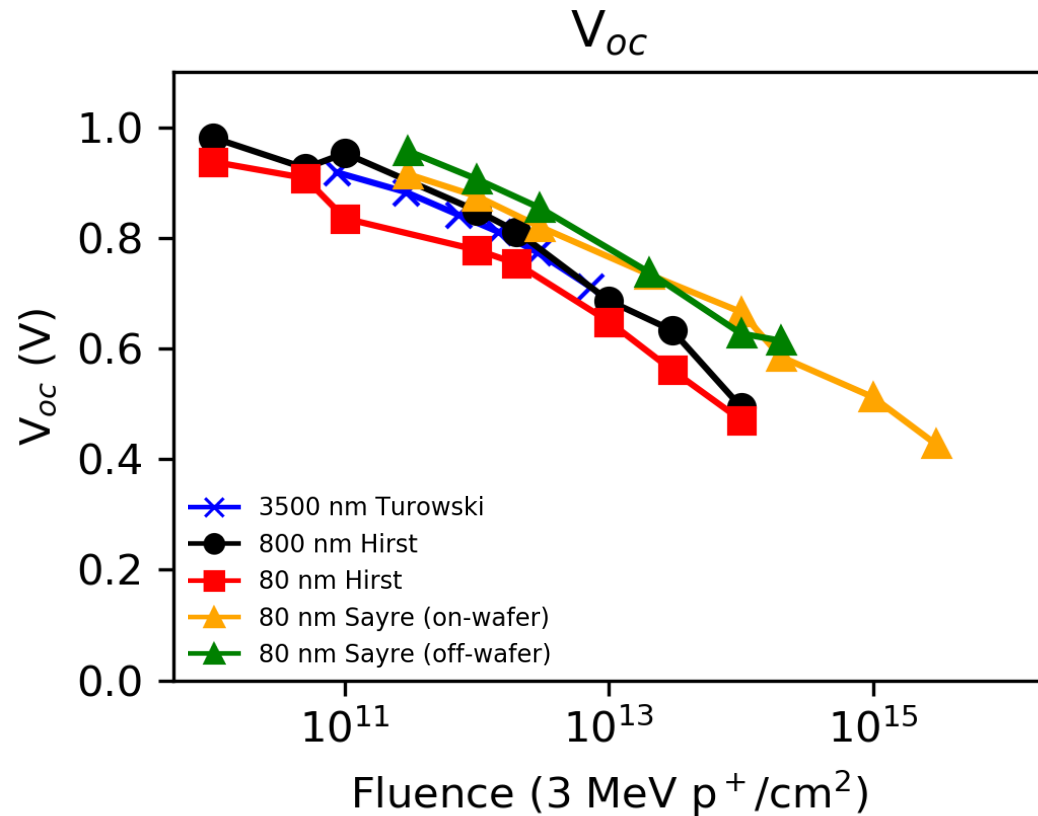
Table 2: comparing off wafer DIV parameters to literature

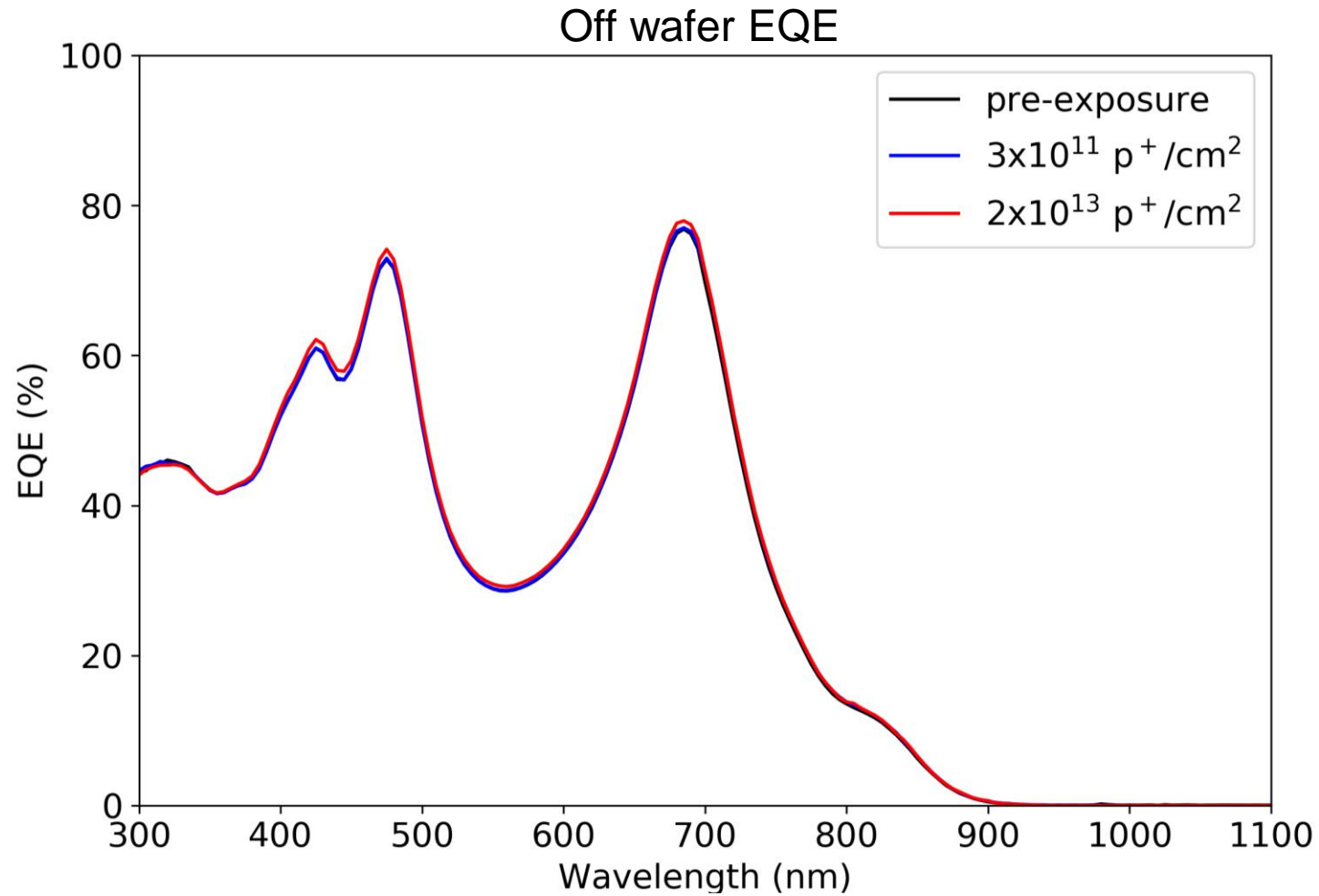
	Thickness (nm)	J_{02} (mA/cm ²)	R_{ser} (Ohm cm ²)	R_{par} (Ohm cm ²)
Chen [5]	205	4.3×10^{-8}	0.8	2.4×10^3
Hirst [1]	800	7.7×10^{-9}	0.99	8.9×10^7
	80	1.4×10^{-6}	13.23	3.8×10^6
This work	80	6.14×10^{-9}	4.54	4.14×10^8

Results - 3 MeV proton irradiation

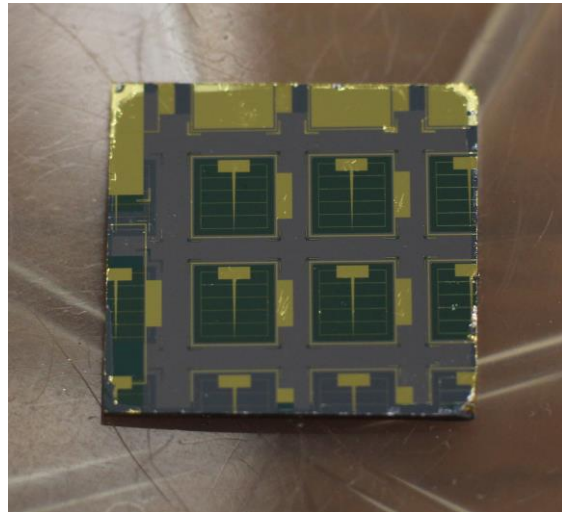


Results - 3 MeV proton irradiation

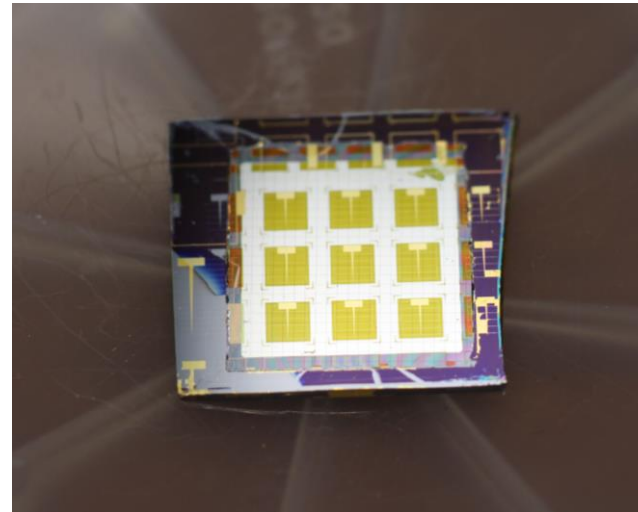




- High levels of radiation tolerance when exposed to high fluences of 3 MeV protons
- Excellent electrical performance: recombination currents and parasitic resistances
- Pathway to 16% AM0 efficiency with nanophotonic light-trapping layer⁶



On-wafer



Off-wafer with planar Ag mirror

- Integrating nanophotonic light-trapping layer
- Anti-reflection coatings
- Optimisation of bonding process
- Further irradiations at different energies

Thank you for your attention!

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